



Material Content Data Sheet



Sales Product Name		ITS711L1		Issued		20. July 2018		
MA#		MA001206818						
Package		PG-DSO-20-31		Weight*		499.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.157	1.83	1.83	18347	18347
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	non noble metal	iron	7439-89-6	3.388	0.68		6789	
wire	non noble metal	copper	7440-50-8	137.580	27.56	28.28	275647	282860
	noble metal	gold	7440-57-5	1.932	0.39	0.39	3870	3870
	encapsulation	organic material	carbon black	1333-86-4	0.677	0.14		1356
encapsulation	plastics	epoxy resin	-	31.142	6.24		62394	
	inorganic material	silicondioxide	60676-86-0	306.681	61.45	67.83	614447	678197
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5501	5501
plating	noble metal	silver	7440-22-4	3.187	0.64	0.64	6385	6385
glue	plastics	epoxy resin	-	0.423	0.08		847	
	noble metal	silver	7440-22-4	1.993	0.40	0.48	3993	4840
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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